

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. (Canceled).
2. (Previously presented) The gas-barrier multi-layer structure according to claim 10, wherein the polyamide resin for the gas-barrier layer A has an oxygen transmission coefficient of 0.01 to 0.15 cc·mm/m²·day·atm when measured at 23°C and 60% relative humidity.
3. (Previously presented) The gas-barrier multi-layer structure according to claim 10, wherein the polyamide resin for the gas-barrier layer A has a melting point of 180 to 235°C.
4. (Currently Amended) The gas-barrier multi-layer structure according to claim 104, wherein the polyamide resin for the gas-barrier layer A has a glass transition point of 85 to 110°C.
5. (Previously presented) The gas-barrier multi-layer structure according to claim 10, wherein the thermoplastic resin for the thermoplastic resin layer B has a Vicat softening point of T_g to T_g + 70°C when measured according to JIS K-7206, wherein T_g is the glass transition point of the polyamide resin for the gas-barrier layer A.

6. (Previously presented) The gas-barrier multi-layer structure according to claim 10, wherein the thermoplastic resin for the thermoplastic resin layer B is a polyolefin.

7. (Previously presented) The gas-barrier multi-layer structure according to claim 10, wherein a thickness of the gas-barrier layer A is 1 to 50% of an overall thickness of the multi-layer structure.

8. (Previously presented) The gas-barrier multi-layer structure according to claim 10, wherein the gas-barrier layer A and the thermoplastic resin layer B are laminated through an intervening adhesive resin layer.

9. (Previously presented) The gas-barrier multi-layer structure according to claim 10, which is made into a form of a multi-layer container.

10. (Previously presented) A gas-barrier multi-layer structure comprising at least one gas-barrier layer A and at least one thermoplastic resin layer B, the gas-barrier layer A comprising a crystallizable polyamide resin produced by polycondensing a diamine component containing 70 mol% or more of m-xylylenediamine with a dicarboxylic acid component containing 80 to 97 mol% of a C₄-C₂₀ α,ω -linear aliphatic dicarboxylic acid and 3 to 20 mol% of isophthalic acid, and the crystallizable polyamide resin having a minimum half crystallization time of 40 to 2,000 s in a measuring temperature range from a glass transition point thereof to less than a melting point thereof when measured by isothermal crystallization according to depolarization photometry,

wherein the polycondensing is conducted by the following steps (1) and (2):

(1) melt-polymerizing the diamine component with the dicarboxylic acid component to produce polyamide; and then,

(2) solid-phase polymerizing the polyamide obtained in step (1), and wherein the relative viscosity (t/t_0) of the polyamide resin thus obtained is in the range of 2.3 to 4.2, and herein "t" denotes the dropping time of a solution, prepared by dissolving 1g of a polyamide resin into 100 ml of 96% sulphuric acid, in a viscosimeter at 25°C, and "t₀" denotes the dropping time of the 96% sulphuric acid at the same condition.

11. (Previously presented) The gas-barrier multi-layer structure according to claim 10, wherein the relative viscosity of the polyamide obtained in the step (1) is in a range of 1.6 to 2.28.

12. (Previously presented) The gas-barrier multi-layer structure according to claim 10, wherein said solid-phase polymerizing is performed at a temperature in a range of 150°C to the melting point of the polyamide.